

Bill of Materials					
Project:	NiMH Battery Charger.PrjPcb				
Revision:	Parameter ProjectRevision not found>				
Project Lead:	<parameter found="" not="" projectauthor=""></parameter>				
Generated On:	2019/11/30 13:18				
Production Quantity:	1				
Currency	CAD				
Total Parts Count:	36				

Designator

LibRef



Supplier 1

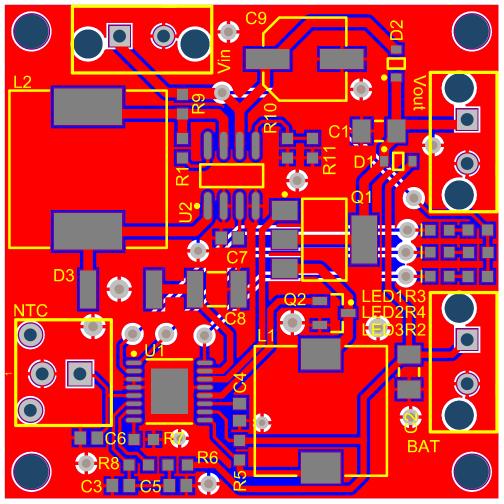
Supplier Part Number 1

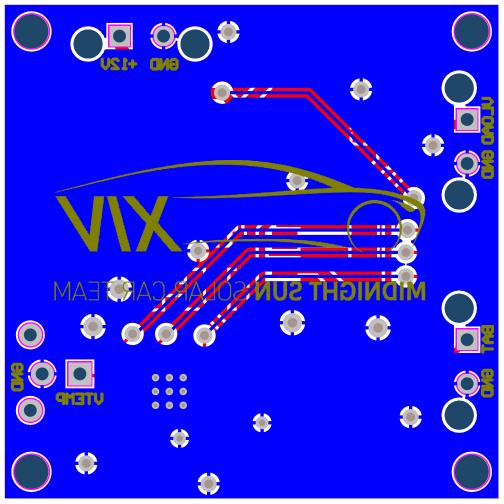
Supplier Unit Pri

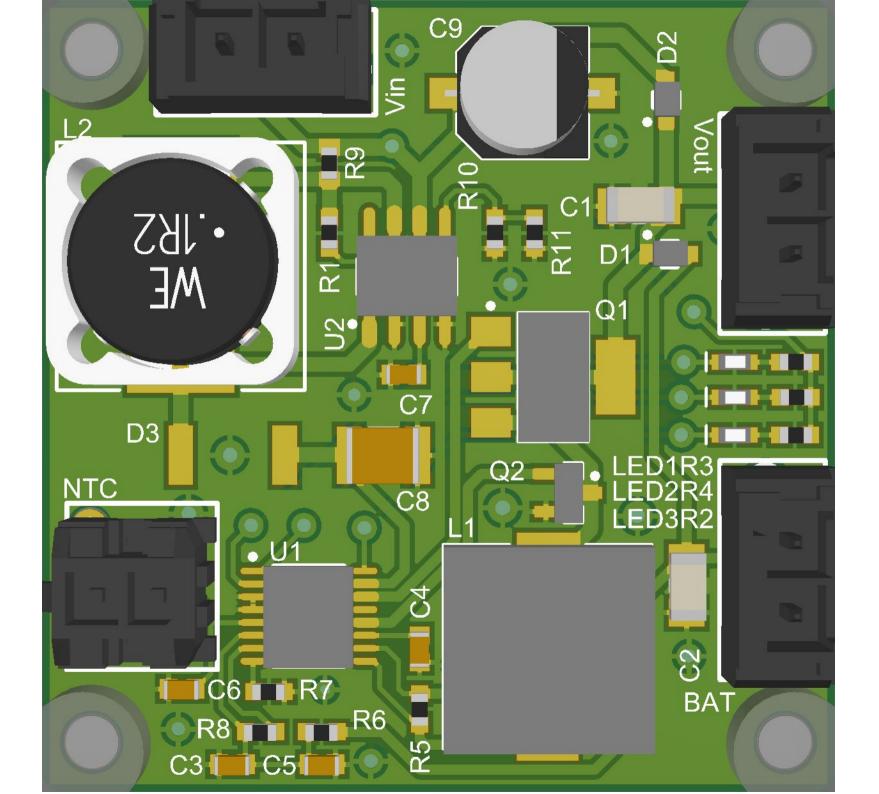
Manufacturer Part Number 1

CAP CER 10uF 50V 20% X5R 1206	C1, C2	Murata	GRT31CR61H106ME01L	Digi-Key	490-12457-1-ND	0.66411
CAP CER 10nF 50V 5% X7R 0603	C3, C5	KEMET	C0603C103J5JACTU	Digi-Key	399-13384-1-ND	0.43831
CAP CER 0.1UF 50V 10% X7R 0603	C4	Kyocera AVX	06035C104KAT2A	Digi-Key	478-5052-1-ND	0.19923
CAPCER 0.068UF 10% 50V X7R 0603	C6	Murata	GCM188R71H683KA57D	Digi-Key	490-8027-1-ND	0.38518
CAP, 1500PF, 50V, 10%, X7R, 0603	C7	KEMET	C0603C152K5RACTU	Digi-Key		
CAPCER 330UF 6.3V X5R 1210	C8	Taiyo Yuden	JMK325ABJ337MM-P	Digi-Key	587-5449-1-ND	6.51
CAPALUM 100UF 20% 35V SMD	C9	Panasonic	EEE-1VA101XP	Digi-Key	PCE3951CT-ND	0.62426
DIODE Schottky Barrier	D1, D2			Digi-Key		
DIODE SCHOTTKY 40V 1A MELF	D3					
IND 10UH 2.8A 59 MOHM SMD	L1	Sumida	CDRH103RNP-100NC-B	Digi-Key	308-1910-1-ND	2.03
IND 180 µH Pow er Inductor	L2					
LED GREEN CLEAR 2V 0603	LED1	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.18595
LED YELLOW CLEAR 2.1V 0603	LED2	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.18595
LED RED CLEAR 2V 0603	LED3	Wurth Electronics	150060RS75000	Digi-Key	732-4978-1-ND	0.18595
CONN 2POS ULTRA-FIT 0.138"	P1, P2, P3	Molex	172287-1102	Digi-Key	WM11701-ND	1.04
CONN 2POS MICRO-FIT 3mm	P4	Molex	43045-0227	Digi-Key	WM10657-ND	1.12
ONSC-PMOS-G1D2S3D4-4	Q1					
MOSFET N-CHANNEL 20V 4A SOT23F	Q2	Toshiba	SSM3K345R,LF	Digi-Key	SSM3K345RLFCT-ND	0.55785
CMP-2002-08252-1	R1, R9	Vishay	CRCW0402180KFKED	Farnell	1571693	
RES 10K OHM 1% 1/10W 0603	R2, R3, R4	Yageo Phycomp	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13282
RES-2	R5					
RES	R6, R8					
CMP-2002-05244-1	R7					
RES 2.21K OHM 1% 1/10W 0603	R10	Yageo	AC0603FR-072K21L	Digi-Key	YAG3586CT-ND	0.13282
RES 47K OHM 1% 1/10W 0603	R11	Vishay	CRCW060347K0FKEA	Digi-Key		
IC Nickel Battery Charger	U1	Analog Devices / Linear	LTC4010CFE#PBF	Digi-Key	LTC4010CFE#PBF-ND	14.33

Manufacturer 1







Electrical Rules Check Report

Class	Document	Message
Warning	NiMH Battery Charger.SchDoc	Net NetR7_2 has no driving source (Pin R7-2,Pin U1-8)
Warning	NiMH Battery Charger.SchDoc	Net NetR10_1 has no driving source (Pin R10-1,Pin R11-1,Pin U2-5)
Warning	NiMH Battery Charger.SchDoc	Net SENSE has no driving source (Pin L1-2,Pin R5-1,Pin U1-9)
Warning	NiMH Battery Charger.SchDoc	Net VCELL has no driving source (Pin C3-1,Pin C5-1,Pin R6-1,Pin R8-2,Pin U1-6)
Warning	NiMH Battery Charger.SchDoc	Net VT EMP has no driving source (Pin C6-1,Pin P4-1,Pin U1-5)
Warning	NiMH Battery Charger.SchDoc	Off grid Net Label VLOAD at 4187.276mil,1000mil
Warning	NiMH Battery Charger.SchDoc	Off grid Net Label VLOAD at 5787.276mil,7200mil

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Design Rules Verification Report

Filename: C:\Users\YCA42\hardware\MSXIV_AuxBatteryCharger\NiMH Battery Charger Rev

Warnings 0 Rule Violations 44

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=10mil) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=10mil) (Max=30mil) (Preferred=10mil) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=20mil) (Conductor Width=10mil) (Air Gap=10mil) (Entries=4)	0
Hole Size Constraint (Min=1mil) (Max=100mil) (All)	4
Hole To Hole Clearance (Gap=10mil) (All),(All)	0
Minimum Solder Mask Sliver (Gap=10mil) (All),(All)	14
Silk To Solder Mask (Clearance=10mil) (IsPad),(All)	14
Silk to Silk (Clearance=10mil) (All),(All)	12
Net Antennae (Tolerance=0mil) (All)	0
Height Constraint (Min=0mil) (Max=1000mil) (Prefered=500mil) (All)	0
Total	44

Hole Size Constraint: (Min=1mil) (Max=100mil) (All) Hole Size Constraint: (106.299mil > 100mil) Pad Free-(1476.378mil,-1476.378mil) on Multi-Layer Actual Hole Size = 106.299mil Hole Size Constraint: (106.299mil > 100mil) Pad Free-(1476.378mil,-98.425mil) on Multi-Layer Actual Hole Size = 106.299mil Hole Size Constraint: (106.299mil > 100mil) Pad Free-(98.425mil,-1476.378mil) on Multi-Layer Actual Hole Size = 106.299mil

Hole Size Constraint: (106.299mil > 100mil) Pad Free-(98.425mil, 98.425mil) on Multi-Layer Actual Hole Size = 106.299mil

Minimum Solder Mask Sliver (Gap=10mil) (All), (All)

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-1(418.779mil,-1135.433mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-10(641.22mil,-1288.976mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-10(641.22mil,-1263.386mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-11(641.22mil,-1263.386mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-12(641.22mil,-1237.795mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-13(641.22mil,-1212.205mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-15(641.22mil,-1186.614mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-2(418.779mil,-1161.024mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-3(418.779mil,-1186.614mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-3(418.779mil,-1212.205mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-5(418.779mil,-1212.205mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-5(418.779mil,-1237.795mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-6(418.779mil,-1263.386mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-6(418.779mil,-1263.386mil) on Top Layer And Pad

Minimum Solder Mask Sliver Constraint: (3.811mil < 10mil) Between Pad U1-7(418.779mil,-1288.976mil) on Top Layer And Pad

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Silk To Solder Mask (Clearance=10mil) (IsPad), (All) Silk To Solder Mask Clearance Constraint: (8.791mil < 10mil) Between Pad C5-1(530mil,-1520mil) on Top Layer And Text "C5" (440mil,-1540mil) on Top Silk To Solder Mask Clearance Constraint: (8.948mil < 10mil) Between Pad C6-1(305mil,-1370mil) on Top Layer And Text "C6" (330mil,-1390mil) on Top Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C9-1(837.716mil,-185mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C9-2(1070mil,-185mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C9-2(1070mil,-185mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (8.213mil < 10mil) Between Pad LED1-2(1345.945mil,-865mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (8.213mil < 10mil) Between Pad LED2-2(1345.945mil,-720mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (8.213mil < 10mil) Between Pad LED3-2(1345.945mil,-790mil) on Top Layer And Track Silk To Solder Mask Clearance Constraint: (9.918mil < 10mil) Between Pad NTC-0(94.882mil,-1047.953mil) on Multi-Layer And Track Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad NTC-0(94.882mil,-1047.953mil) on Multi-Layer And Track Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad NTC-0(94.882mil,-1284.173mil) on Multi-Layer And Track Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad NTC-0(94.882mil,-1284.173mil) on Multi-Layer And Track Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad NTC-0(94.882mil,-1284.173mil) on Multi-Layer And Track Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad NTC-0(94.882mil,-1284.173mil) on Multi-Layer And Track

Silk to Silk (Clearance=10mil) (All),(All) Silk To Silk Clearance Constraint: (8.324mil < 10mil) Between Arc (616.535mil,-644.488mil) on Top Overlay And Text "U2" (600mil,-695mil) on Top Silk To Silk Clearance Constraint: (6.811mil < 10mil) Between Text "1" (37.402mil,-1173.937mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.079mil < 10mil) Between Text "L2" (45mil,-275mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (7.516mil < 10mil) Between Text "LED2" (1135mil,-995mil) on Top Overlay And Text "R4" (1270mil,-995mil) on Top Silk To Silk Clearance Constraint: (8.349mil < 10mil) Between Text "LED3" (1135mil,-1050mil) on Top Overlay And Text "R2" (1270mil,-1050mil) on Top Silk To Silk Clearance Constraint: (5.709mil < 10mil) Between Text "NTC" (45mil,-990mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.907mil < 10mil) Between Text "R2" (1270mil,-1050mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.963mil < 10mil) Between Text "R3" (1270mil,-945mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.685mil < 10mil) Between Text "R4" (1270mil,-995mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.685mil < 10mil) Between Text "R4" (1270mil,-995mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (9.685mil < 10mil) Between Text "R4" (1270mil,-995mil) on Top Overlay And Track Silk To Silk Clearance Constraint: (8.051mil < 10mil) Between Text "U1" (455mil,-1115mil) on Top Overlay And Track

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